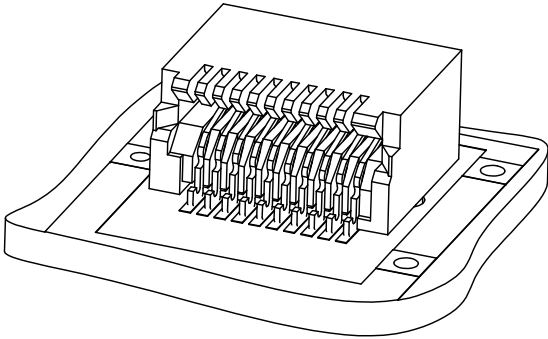


SALES ASSEMBLY DRAWINGS FOR SMALL FORM-FACTOR AND Z AXIS PLUGGABLE CONNECTORS

CKT SIZE	PART NUMBER	TOOLED	DESCRIPTION	'A'	'B'	'C'	'D'	MULTI-SOURCE AGREEMENT	CONNECTOR DRAWING	CIRCUIT BOARD DRAWING
20	74441-0001	YES	PLATED PER NOTE 2	1.10/.043	11.00/.433	9.40/.370	9.60/.378	SFP	PAGE 2	PAGE 3
	74441-0004	NO*	PLATED PER NOTE 2	0.76/.030						
	74441-0010	YES	PLATED PER NOTE 3	1.10/.043						
	74441-0014	NO*	PLATED PER NOTE 3	0.76/.030						
	74441-0021	YES	PLATED PER NOTE 4	1.10/.043						
	74441-0031	YES	PLATED PER NOTE 5	1.10/.043						
30	74441-0041	YES	PLATED PER NOTE 6	1.10/.043	15.00/.591	13.40/.528	13.60/.535	XFP	PAGE 2	PAGE 4
	74441-0007	YES	PLATED PER NOTE 2	1.10/.043						
	74441-0017	YES	PLATED PER NOTE 3	1.10/.043						
40	74441-0027	YES	PLATED PER NOTE 4	1.10/.043	19.00/.748	17.40/.685	17.60/.693		PAGE 2	PAGE 5
	74441-0005	YES	PLATED PER NOTE 2	1.10/.043						
	74441-0015	YES	PLATED PER NOTE 3	1.10/.043						
50	74441-0025	YES	PLATED PER NOTE 4	1.10/.043	23.00/.906	21.40/.843	21.60/.850		PAGE 2	PAGE 6
	74441-0008	YES	PLATED PER NOTE 2	1.10/.043						
	74441-0018	YES	PLATED PER NOTE 3	1.10/.043						
	74441-0028	YES	PLATED PER NOTE 4	1.10/.043						
	74441-0038	YES	PLATED PER NOTE 5	1.10/.043						
70	74441-0003	YES	PLATED PER NOTE 2	1.10/.043	31.00/1.220	29.40/1.157	29.60/1.165	XENPAK XPAK X2	PAGE 2	PAGE 7
	74441-0013	YES	PLATED PER NOTE 3	1.10/.043						
	74441-0023	YES	PLATED PER NOTE 4	1.10/.043						
	74441-0033	YES	PLATED PER NOTE 5	1.10/.043						

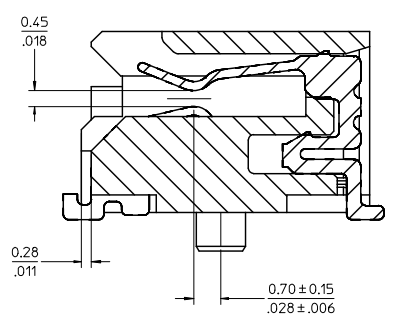
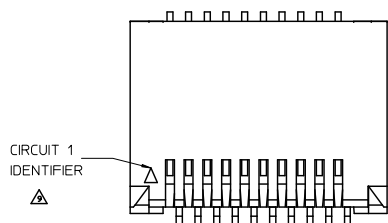
NOTES

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
- PLATING:
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.
- PLATING:
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL
- PLATING:
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL; LUBRICATED
SOLDER AREA: GOLD FLASH OVER 2.54 μm MIN NICKEL.
- PLATING:
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL,
SOLDER AREA: GOLD FLASH OVER 2.54 μm MIN NICKEL.
- PLATING:
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm NICKEL,
SOLDER AREA: GOLD FLASH OVER 2.54 μm MIN NICKEL.
- TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 FOR 20, 30 AND 40 CIRCUIT CONNECTORS
TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.15/.006 FOR 70 CIRCUIT CONNECTOR
- * CONTACT PLANT FOR MORE INFORMATION
- DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
- CIRCUIT 1 IDENTIFIER LOCATED ON ALL PART NUMBERS

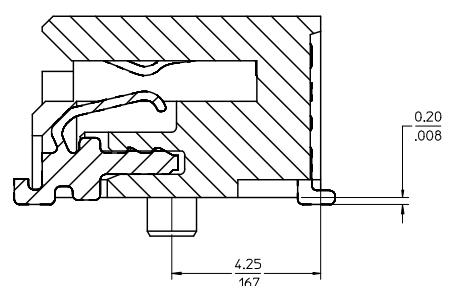
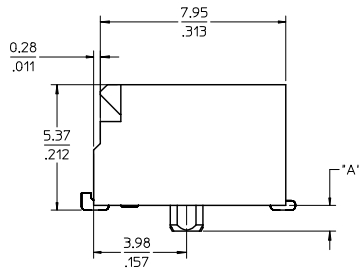
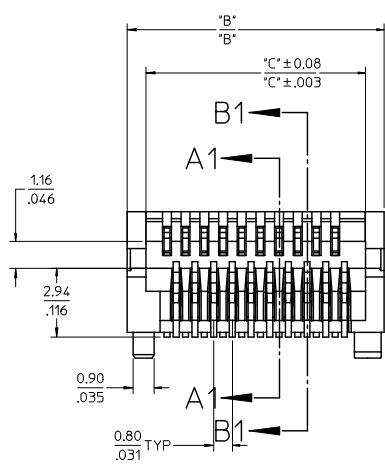


ADD -0041 EC NO: UCP2009-1455 DRWN:SBARRA 2009/01/15 CHKD:SMART 2009/01/15 APPR:SMILLER 2009/01/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± .005 1 PLACE ± 0.25 ± .010 ANGULAR ± 1/2°	MM/IN	1:1	METRIC	
	DRAWN BY: HAVERY CHECKED BY: KSWEENEY APPROVED BY: MBANAKIS	DATE: 00/04/06 DATE: 00/04/06 DATE: 00/04/06	TITLE	SALES ASSEMBLY Z AXIS PLUGGABLE PCB CONNECTOR		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO. MBANAKIS DOCUMENT NO. SD-74441-001	MOLEX INCORPORATED		

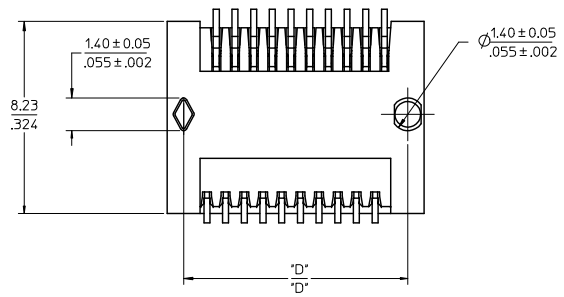
13 12 11 10 9 8 7 6 5 4 3 2 1



SECTION A1-A1
SCALE 12:1



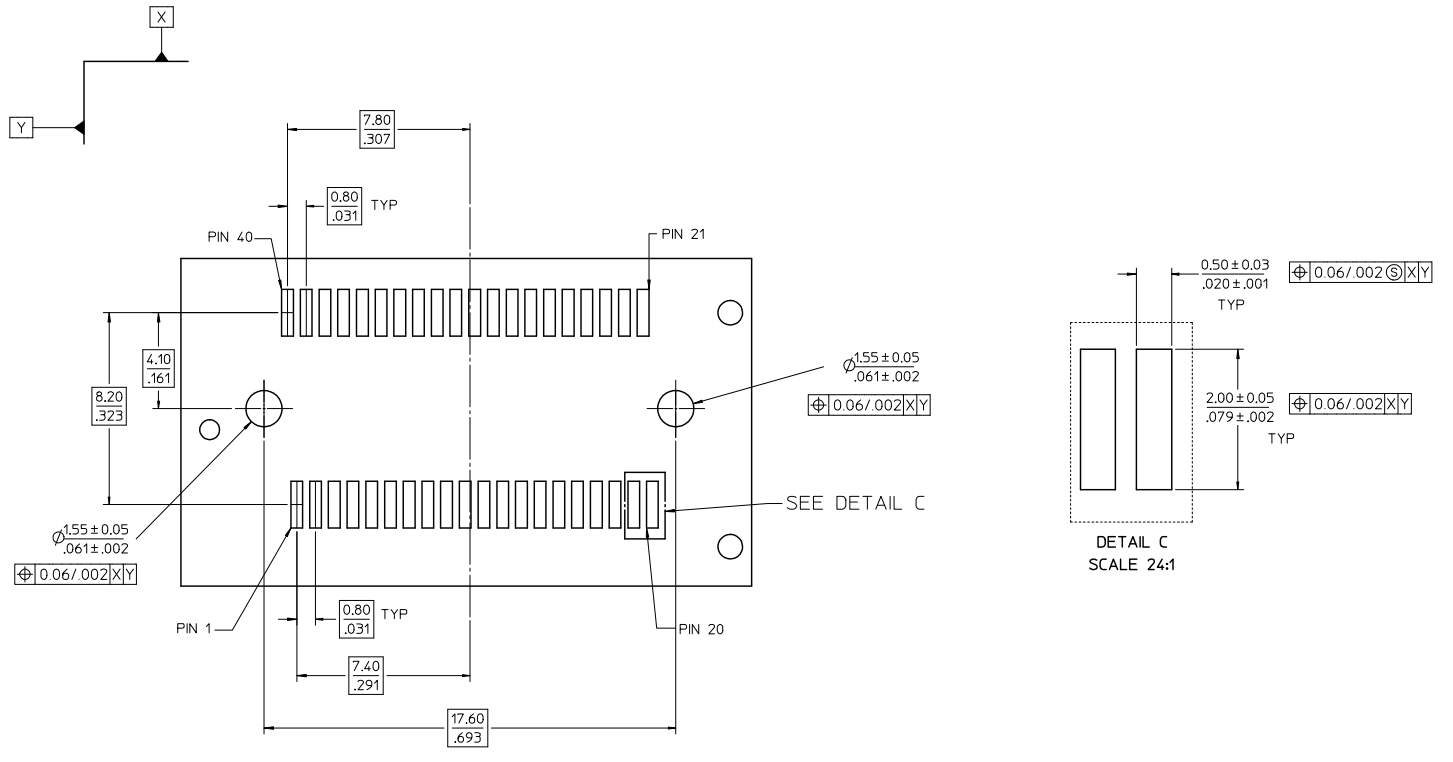
SECTION B1-B1
SCALE 12:1



SEE SHEET 1 EIC NO. LEP2009-1455 2009/01/15 DRWNS BARBA 2009/01/15 CHKD:SMART 2009/01/16 APPR:SMILLER	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 6:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± .01 ± .005	3 PLACES ± .02 ± .005	2 PLACES ± .03 ± .005	1 PLACE ± .04 ± .010	DRAWN BY HAVERY 00/04/06	DATE 00/04/06	TITLE SALES ASSEMBLY Z AXIS PLUGGABLE PCB CONNECTOR		
		ANGULAR ± 1/2°				APPROVED BY MBANAKIS 00/04/06	DATE 00/04/06	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-74441-001	SHEET NO. 2 OF 7		

12 11 10 9 8 7 6 5 4 3 2 1

13 12 11 10 9 8 7 6 5 4 3 2 1

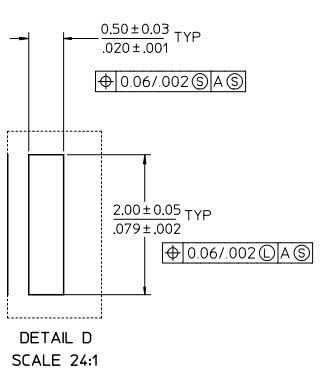
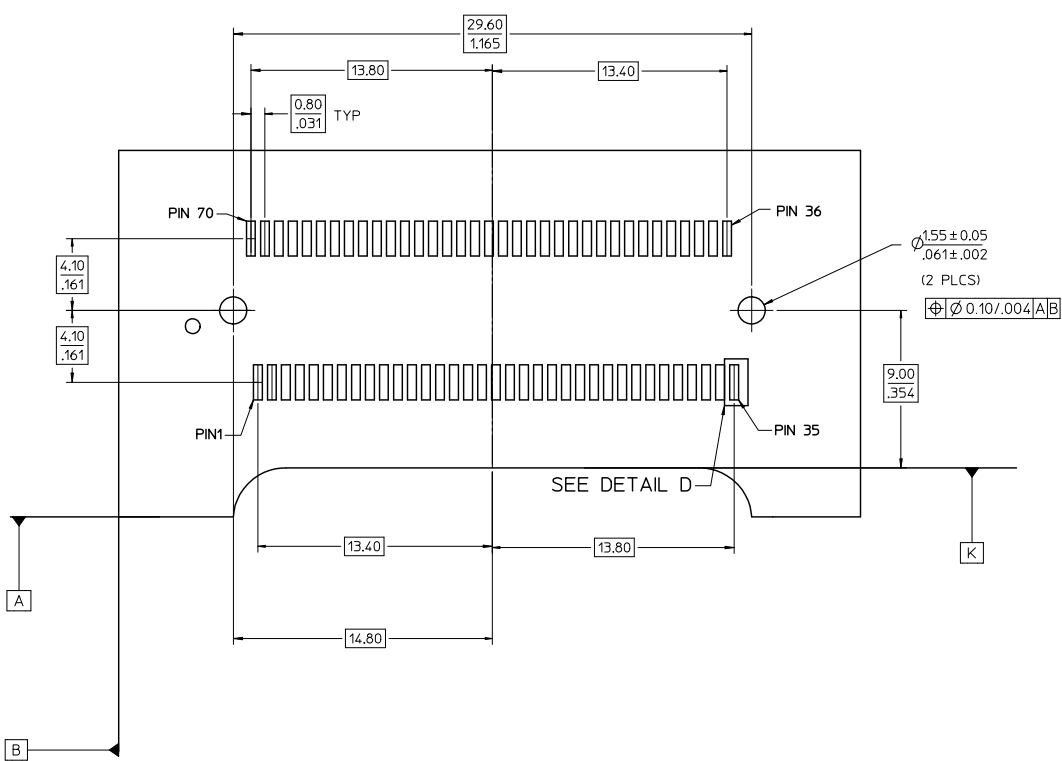


40 CIRCUIT MOTHER BOARD
RECOMMENDED PCB LAYOUT

SEE SHEET 1 EC NO. UCP2009-1455 DRAWN BY BARBA 2009/07/15 CHECKED BY CHKCRSMRT 2009/07/15 APPR: SMILLER 2009/07/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	INCH	MM/IN	6:1	METRIC	☉	
	▽=0	4 PLACES ±---	±---	DRAWN BY	DATE	TITLE		
		3 PLACES ±---	±---	HAVERY	00/04/06	SALES ASSEMBLY Z AXIS PLUGGABLE PCB CONNECTOR		
	2 PLACES ±0.13	±.005	CHECKED BY	DATE	MOLEX INCORPORATED			
	1 PLACE ±0.25	±.010	KSWEENEY	00/04/06	MATERIAL NO. DOCUMENT NO. SHEET NO.			
	ANGULAR ±1/2°		APPROVED BY	DATE	SD-74441-001		5 OF 7	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MBANAK1S	00/04/06	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

12 11 10 9 8 7 6 5 4 3 2 1

13 12 11 10 9 8 7 6 5 4 3 2 1



70 CIRCUIT MOTHER BOARD
RECOMMENDED PCB LAYOUT

SEE SHEET 1 EIC NO. UEP2009-1655 DRAWN BY: DRWNS/BARRA 2009/01/15 CHECKED BY: CHAD/SWART 2009/01/15 APPR: SMILLER 2009/01/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	mm INCH 4 PLACES ± ± 3 PLACES ± ± 2 PLACES ± 0.13 ± .005 1 PLACE ± 0.25 ± .010 ANGULAR ± 1/2°	MM/IN	6:1	METRIC	☉ THIRD ANGLE PROJECTION
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: HAVERY DATE: 00/04/06 CHECKED BY: KSWEENEY DATE: 00/04/06 APPROVED BY: MBANAKIS DATE: 00/04/06	TITLE	SALES ASSEMBLY Z AXIS PLUGGABLE PCB CONNECTOR	
	REV	SIZE C	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-74441-001	MOLEX INCORPORATED THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

12 11 10 9 8 7 6 5 4 3 2 1